

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJMN3010L
Package Type :	DFNWB2x2-6L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	5.2711%
Lead Frame	Cu	7440-50-8	97.613%	52.6149%
	Fe	7439-89-6	2.20%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.10%	
	Ag	7440-22-4	0.007%	
Epoxy	Silver	7440-22-4	77.00%	1.7662%
	Acrylic resin	Trade Secret	6.00%	
	Polybutadiene derivative	Trade Secret	4.00%	
	Acrylate	Trade Secret	8.00%	
	Epoxy resin	Trade Secret	2.00%	
	Additive	Trade Secret	1.00%	
	Butadiene copolymer	Trade Secret	1.00%	
	Peroxide	Trade Secret	1.00%	
Wire	Copper	7440-50-8	99.9978%	2.0422%
	Other	/	0.0022%	
Mold Compound	Epoxy resin A	Trade Secret	3.00%	34.0003%
	Epoxy resin B	Trade Secret	3.00%	
	Phenol Resin	Trade Secret	3.00%	
	Silica(Amorphous) A	60676-86-0	83.50%	
	Silica(Amorphous) B	7631-86-9	7.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Sn	7440-31-5	99.90%	4.3052%
	Others	/	0.10%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.